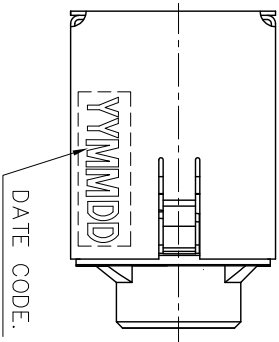
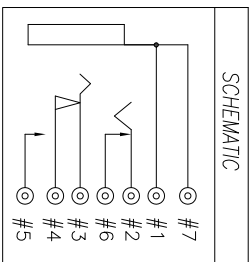
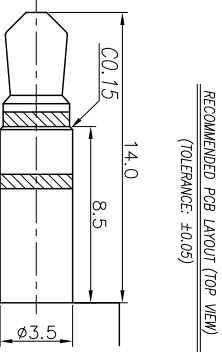
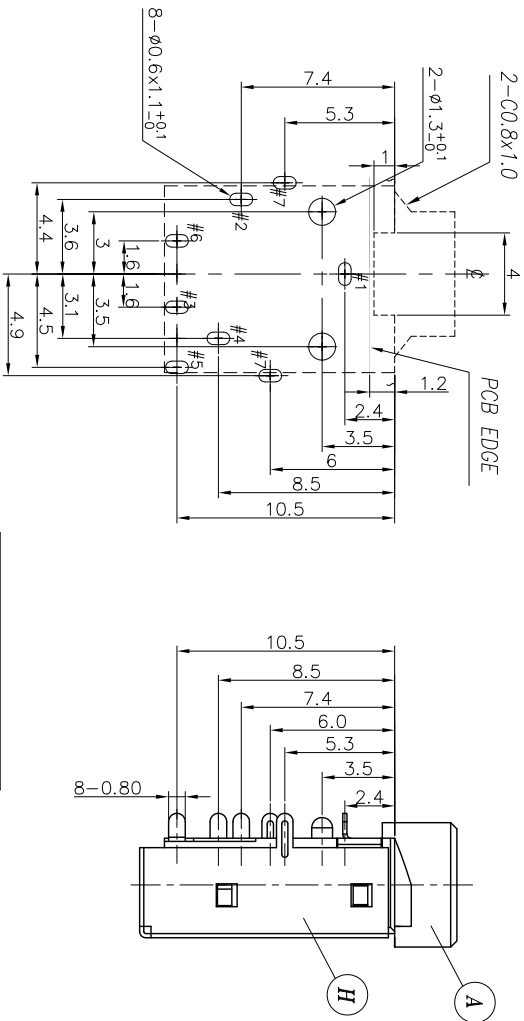
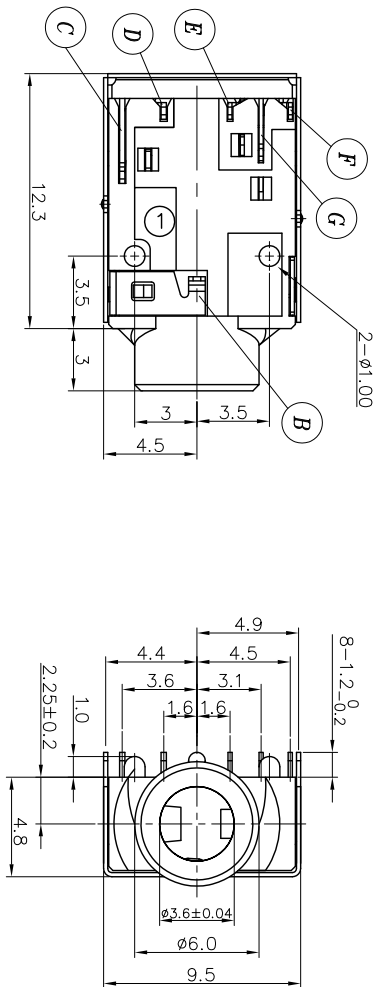


REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
C	ECN NO.S110728		Seon	2011.10.31
D	ECN NO.S120447		Seon	2012.06.07
E	ECN NO.S120750		Seon	2012.07.31



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100M Ω MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 30m Ω MAX.
 - INSULATION VOLTAGE WITHSTAND:
500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TES: 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE: 0.4 - 3kgf.
 - WITHDRAWAL FORCE: 0.3 - 2kgf.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50m Ω MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50M Ω MIN.
 - PACKAGING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
 - HALOGEN PRODUCT IDENTIFICATION MARK ON JACK:
 - HALOGEN PRODUCT IDENTIFICATION LABEL ON PACKAGING:
 - FOR LEAD-FREE PROCESS.

NO.	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	UL 94V-0	BLACK
B	EARTH	1	COPPER ALLOY 0.2t	Ag 20μ" OVER 50μ" NICKEL PLATING.
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag 20μ" OVER 60μ" NICKEL PLATING.
D	SHUNT TERMINAL-A	1	BRASS 0.25t	
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	120μ" Sn ON SOLDER TAIL AREA ALL OVER 50μ" Ni.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	Ni 60μ" MIN.
H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	60μ" FLASH ON CONTACT AREA

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X. :±0.5	X : ±2°
XX : ±0.3	X.X : ±1°
XXX : ±0.2	
X.XXX : ±0.1	

TITLE	3.5φ PHONE JACK
DWN	Seon PART NO. 2SJ-1351-023
CHKD	TOM SCALE: 4:1 UNIT: mm
APVD	QUAN SIZE: A3 SHEET: 1 OF 1 REV: E

CUSTOMER COPY